	2016 INTERNATIONAL SYMPOSIUM ON 3D POWER ELECTRONICS INTEGRATION & MANUFACTURING		
	13-Jun-16	14-Jun-16	15-Jun-16
	MONDAY	TUESDAY	WEDNESDAY
8:00 AM - 9:55 AM	TUTORIALS THE WORLD OF PACKAGING TECHNOLOGIES and THE CRITICAL ISSUES	PLENARY ROAD MAPPING Ernier Parker (Crane), Chair Invited Speakers: Brian Narveson (PSMA) iNEMI	<b>MANUFACTURABILITY</b> Jared Hornberger (Wolfspeed), Chair  Invited Speakers: TBA
9:55 AM - 10:20 PM	3D Power Electronics & Additive Mfg. by Dr Douglas Hopkins	Break	Break
10:20 AM - 12:15PM	Materials & Assembly for 3D Integration by Dr Guo-Quan (GQ) Lu Thermal & Reliability Issues in 3D Integration by Dr Patrick McCluskey	MULTIPHYSICS MODELING & SIMULATION Zhenxian Liang (ORNL), Chair Invited Speakers: TBA	<b>QUALITY &amp; RELIABILITY</b> Patrick McCluskey (UMD), Chair  Invited Speakers: TBA
12:15 PM 1:15 PM	Lunch - Tutorial Attendees (Networking)	Lunch (Networking)	Lunch (Networking)
1:15 PM - 3:10 PM	ADDITIVE MANUFACTURING Ola Harrysson (NCSU), Chair Govindarajan Muralidharan (ORNL), Co-Chair  Invited Speakers: TBA	MATERIALS Thomas Lai, Chair Invited Speakers: Katsuaki Suganuma	PASSIVE COMPONENTS  Khai Ngo (VT), Chair  Invited Speakers: Charlie Sullivan
3:10 PM - 3:35 PM	Break	Break	
3:35PM - 5:30PM	THERMAL MANAGEMENT & SYSTEMS INTEGRATION Sreekant Narumanchi (NREL), Chair Invited Speakers: Eric Dede Brij Singh	EMBEDDED COMPONENTS Paul McCloskey, Chair Invited Speakers: Cian O'Mathuna	Break (Networking) NCSU LAB TOURS PREES PACKAGING ADD MFG & LOGISTICS CTR
5:30 PM - 7:30 PM	WELCOME RECEPTION DIALOGUE PRESENTATIONS & VENDOR EXHIBITS	NETWORING RECEPTION DIALOGUE PRESENTATIONS & VENDOR EXHIBITS	